

## 908 Series

Wakefield-Vette's 900 Series Heat Sinks for Chipset can match up to devices from Intel, Broadcom, Xilinx, TI, Motorola, ATI, AMD, Nvidia, Vishay, Pow erex, Infineon, Microsemi, and many more.

These heat sinks are designed for air flow applications in the Telecom, Data Center, Networking, Cloud Computing, and many more Industries.

**Material:** AL 6063

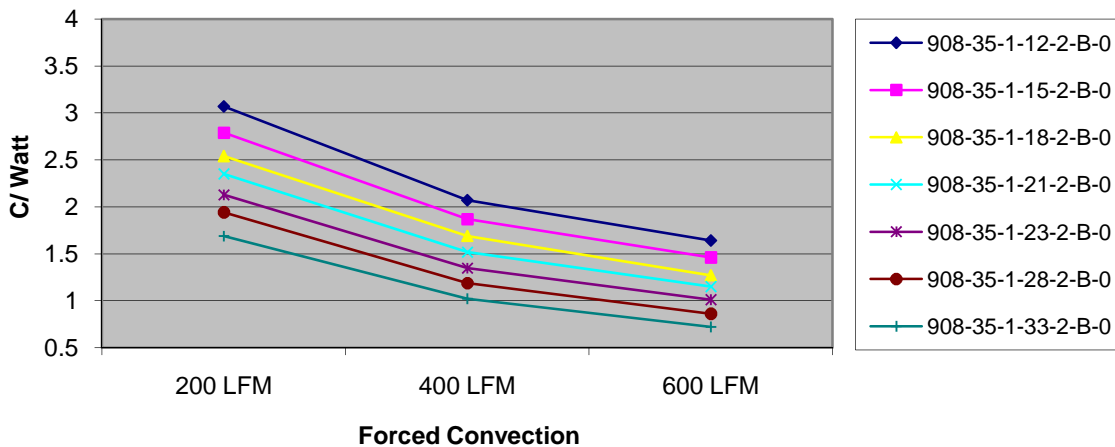


**Finish:** Black Anodize



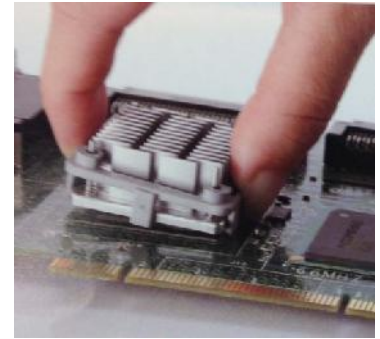
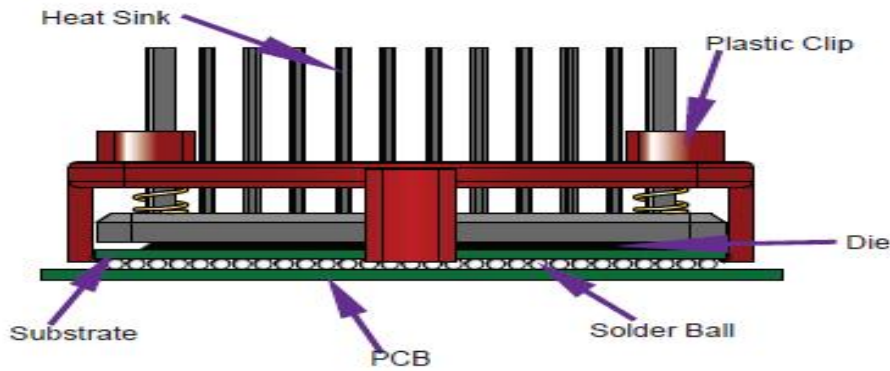
PART #	HEIGHT (mm)	CHIP SIZE (mm)	NATURAL CONVECTION	FORCED CONVECTION (C/W)		
				200 LFM	400 LFM	600 LFM
908-35-1-12-2-B-0	12	35	11.1 C/W	3.07 C/W	2.07 C/W	1.64 C/W
908-35-1-15-2-B-0	15	35	10.58 C/W	2.79 C/W	1.87 C/W	1.46 C/W
908-35-1-18-2-B-0	18	35	10.06 C/W	2.54 C/W	1.69 C/W	1.27 C/W
908-35-1-21-2-B-0	21	35	9.53 C/W	2.35 C/W	1.52 C/W	1.15 C/W
908-35-1-23-2-B-0	23	35	8.75 C/W	2.13 C/W	1.35 C/W	1.01 C/W
908-35-1-28-2-B-0	28	35	7.93 C/W	1.94 C/W	1.19 C/W	.86 C/W
908-35-1-33-2-B-0	33	35	7.11 C/W	1.69 C/W	1.02 C/W	.72 C/W

### THERMAL PERFORMANCE:



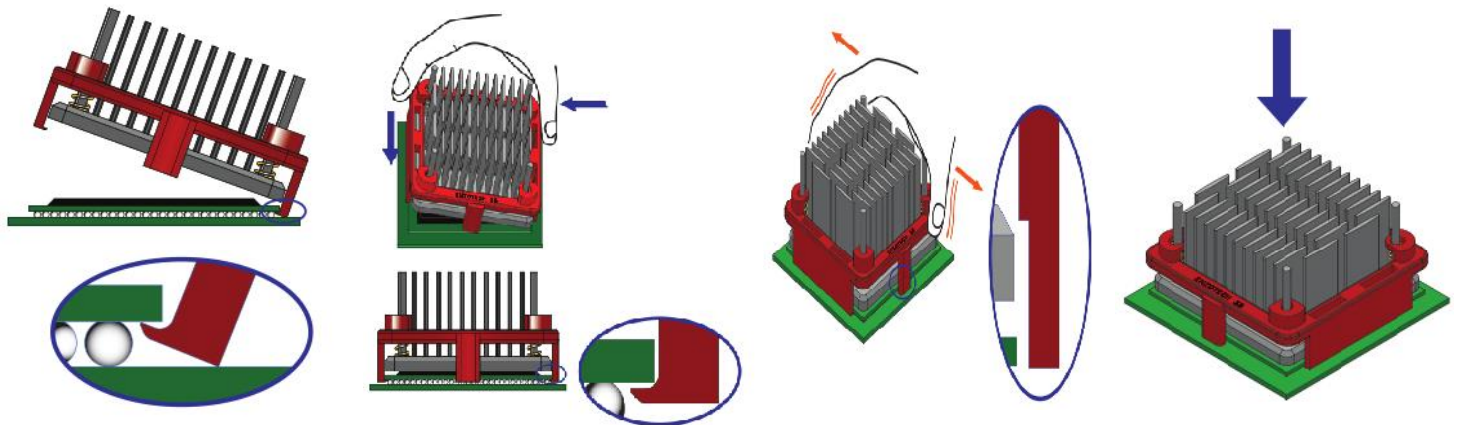
Series	Chip Size	Construction	Height	Chip Height	Finish	Interface	
908-	19-	1= Elliptical Fin	12-	1-	B = BLK ANO	1	
	19		12 = 11.6	1 = .9-2.1			0 = None
	21		15 = 14.6	2 = 2.2-3.4			1 = T725
	23		18 = 17.6				
	27		21 = 20.6				
	29		23 = 22.6				
	31		28 = 27.6				
	33		33 = 32.6				
	35						
	37.5						
40							

Thermal Cooling Solutions from Smart to Finish



Wakefield-Vette's heat sink assembles onto chip set using the space that is between the PCB and the substrate of the solder balls. The solder balls provide a minimal gap of .5mm to .7mm. Attachment feature is below a .4mm thickness. The clipping system will not interfere or damage chip. Contact area is the edge of chip.

**ASSEMBLY INSTRUCTION:**



**Step 1:** Hook the clip under one side of the BGA chip set.

**Step 2:** Rotate assembly down until opposite side clip engages substrate edge of BGA chip set.

**Step 3:** Make sure the solder rods are clearing from edges of BGA chip set.

**Step 4:** Press firmly down to make sure clips fully engage edges of chip set. Heat Sink should not move around easily.

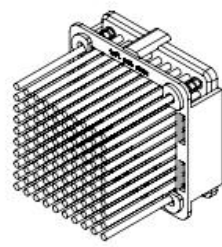
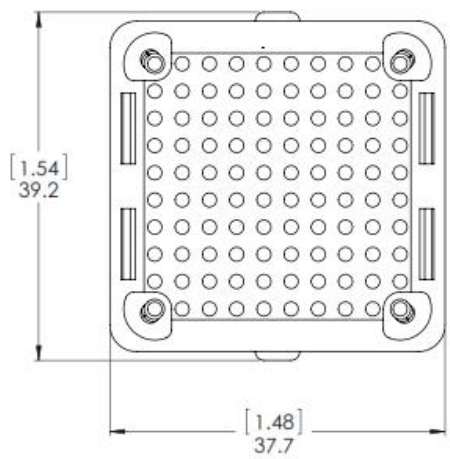
**Random Vibration Test**

Frequency : 5 Hz to 500 Hz  
 Acceleration : 3.13 grms  
 P.S.D : 0.01 g<sup>2</sup>/HZ (5 Hz)  
 0.02 g<sup>2</sup>/HZ (20 Hz to 500 Hz)  
 Test Axis : X, Y, Z axis  
 Test Time : 10 mins (Each axis)  
 Total Test Time : 30 mins

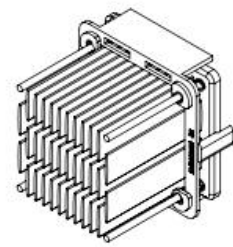
**SHOCK TEST SPECIFICATION :**

Wave Form : Half sine wave  
 Acceleration : 50 g  
 Duration Time : 11 ms  
 No. of Shock : Each axis 3 times  
 Shock Direction : ±X, ±Y, ±Z axis  
 Reliability & Communication  
 Testing Instruments

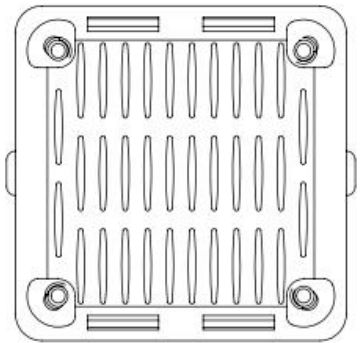
8 7 6 5 4 3 2 1



CONSTRUCTION CODE- 2  
PIN FINS  
10 X 10 PIN ARRAY =  
100 FINS, 1.6 mm DIA.



CONSTRUCTION CODE- 1  
ELLIPTICAL FINS  
34 FINS, 8.5 Lg X 0.85 W mm  
4 CORNER PIN FINS



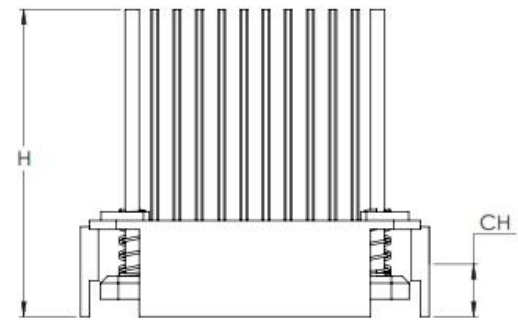
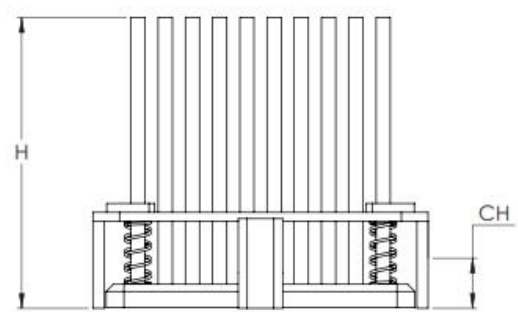
SHOWN ROTATED 90 DEG

HEIGHT ( H )  
CODE ACTUAL mm

12-	11.6
15-	14.6
18-	17.6
21-	20.6
23-	22.6
28-	27.6
33-	32.6

CHIP HEIGHT ( CH )  
CODE ACTUAL RANGE mm

1-	0.9 to 2.1
2-	2.2 to 3.4



**908 SERIES FOR 35mm CHIPS**

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	APPROVALS	DATE:			DRAWING NOT TOSCALE
	DRAWN:	10/23/2014	REVISION:		
	CHK:		SCALE: 2:1		
MATERIAL: <b>6063-T5 AL ALLOY</b>	DSGN ENG:	10/23/2014	MODEL INFO: MBA35052-no lp		
FINISH: <b>BLACK ANODIZE</b>	MFG ENG:				
	QA:				

A

A

SH\_SIZE: B

8 7 6 5 4 3 2 1